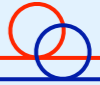
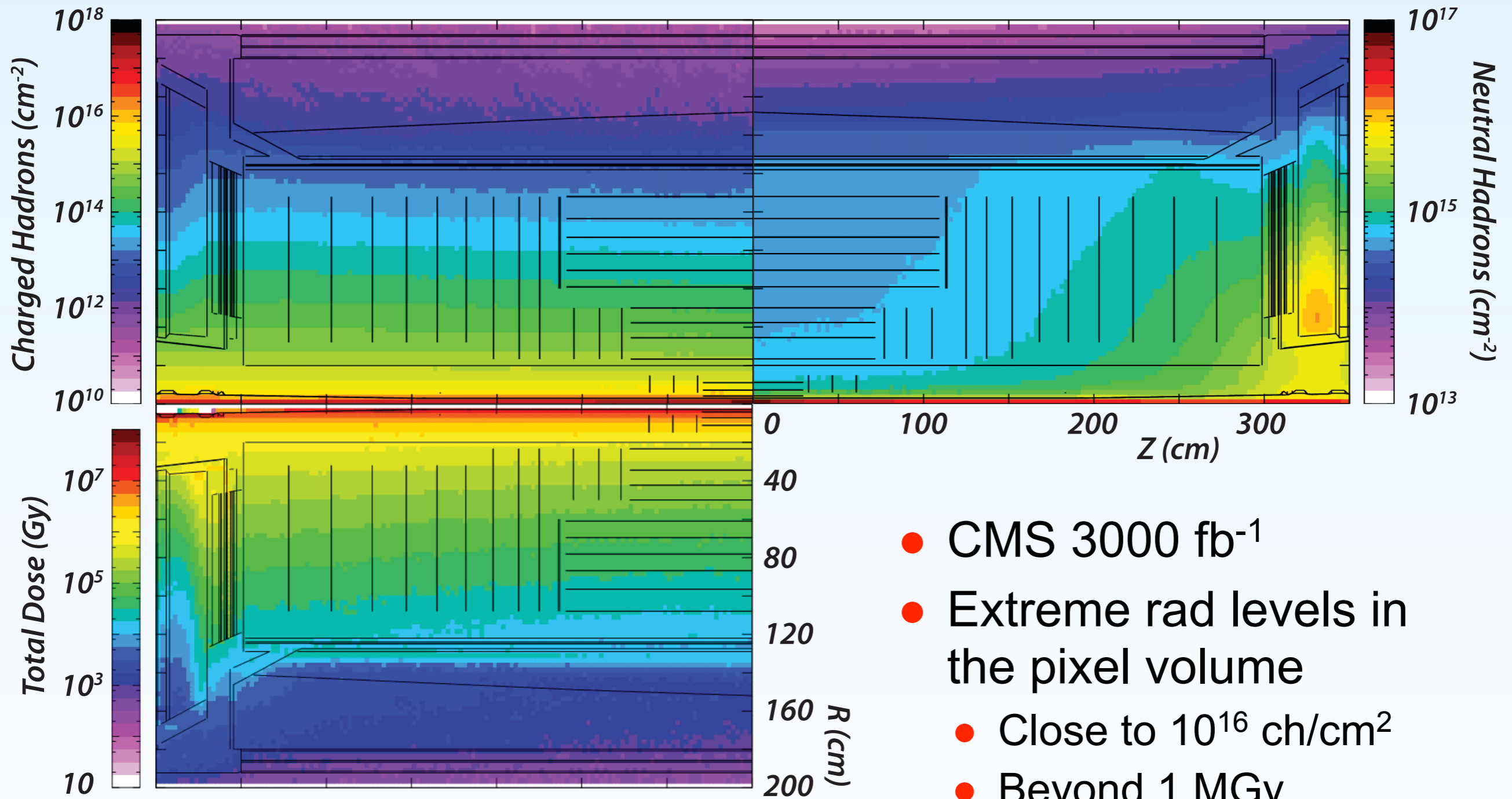
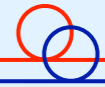


Optical link prospects for Phase II Pixels

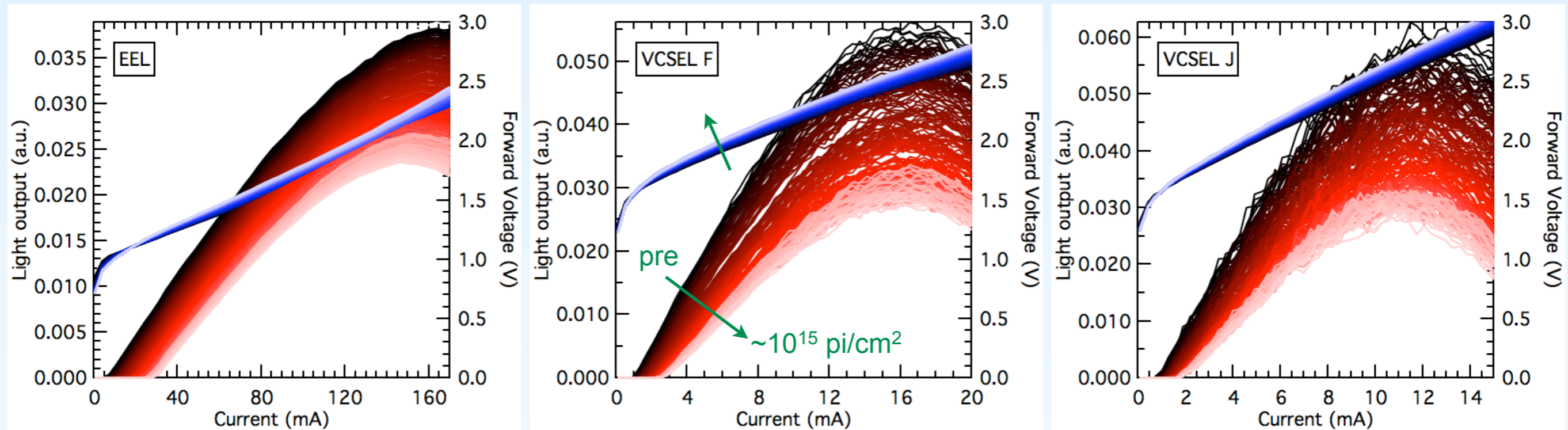
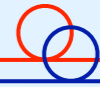


- Some remarks on the possibilities of using Optical Links in the innermost regions of CMS after LS3
- Radiation effects
- Power dissipation
- Size

Radiation levels

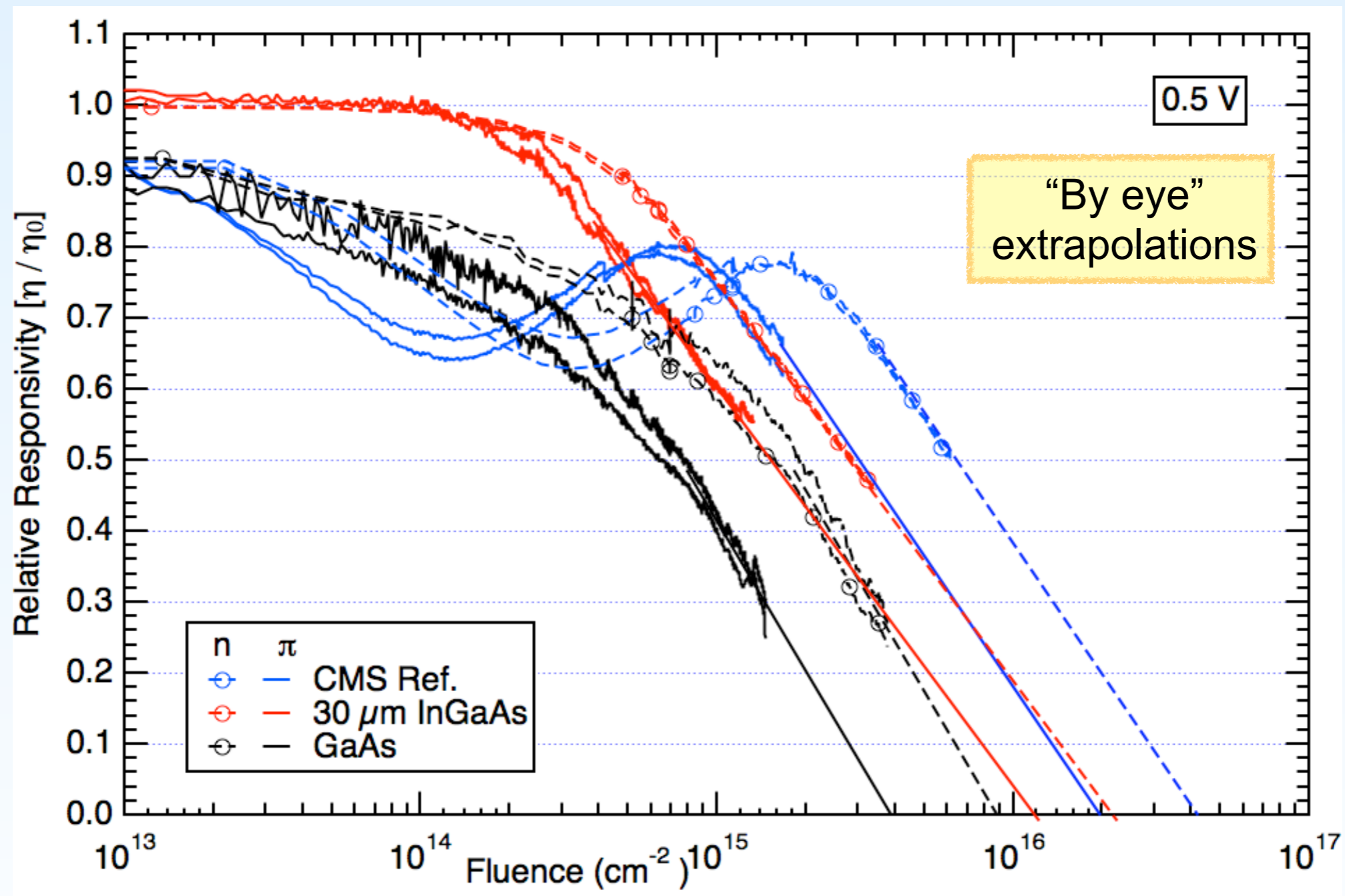
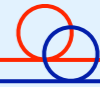


- CMS 3000 fb^{-1}
- Extreme rad levels in the pixel volume
 - Close to 10^{16} ch/cm^2
 - Beyond 1 MGy
 - Several 10^{15} n/cm^2



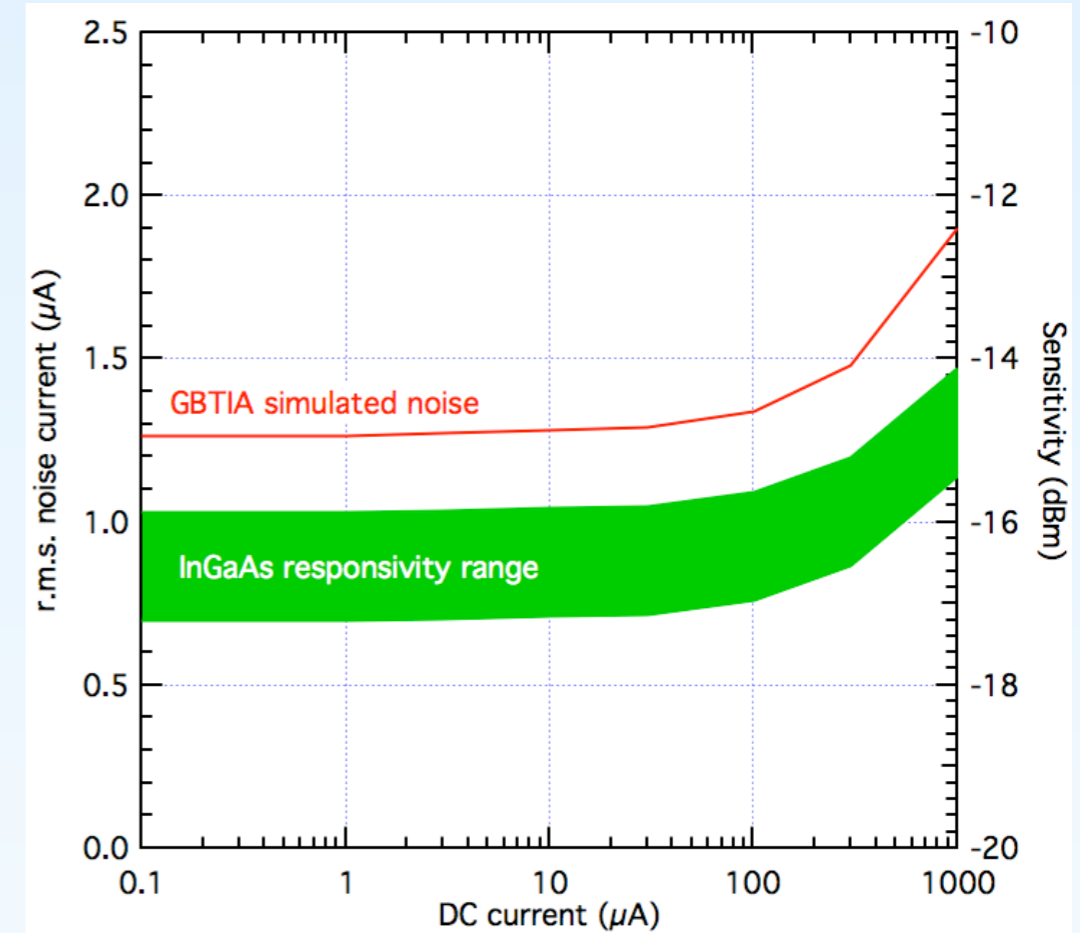
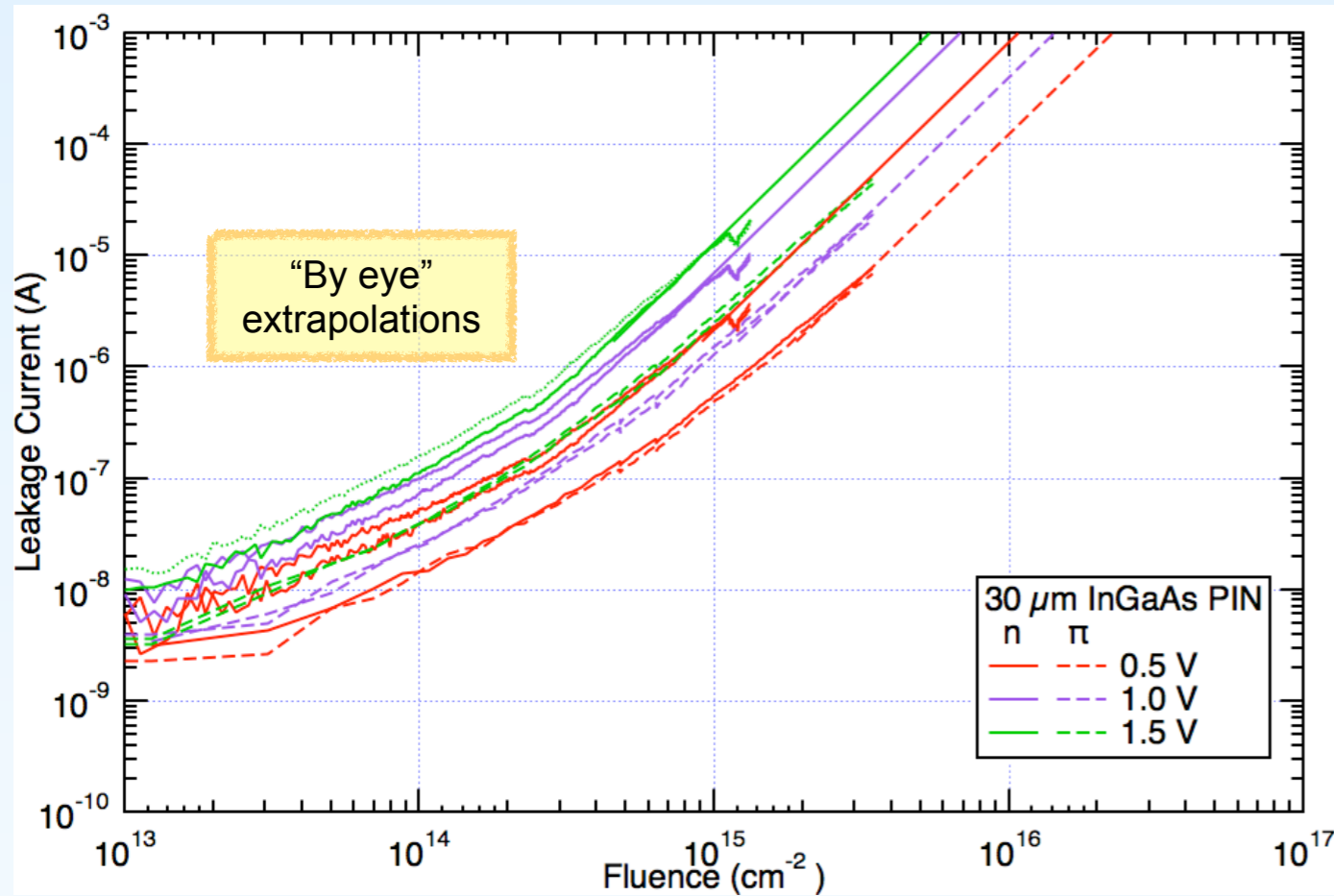
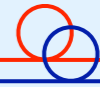
- By eye, might assume lasers could survive “a few” $10^{15} /\text{cm}^2$
 - Need to be able to track threshold changes
 - Deal with output amplitude degradation in link budget
- Annealing helps a bit
 - Gain a factor of two in reduction of damage at SLHC fluxes

Impact of PD Responsivity loss



- GaAs non-functional after around 4×10^{15} pi/cm²
- InGaAs non-functional after around 10^{16} pi/cm²
- No annealing

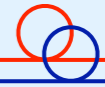
Impact of PD Leakage Current



Reminder: no leakage in GaAs devices

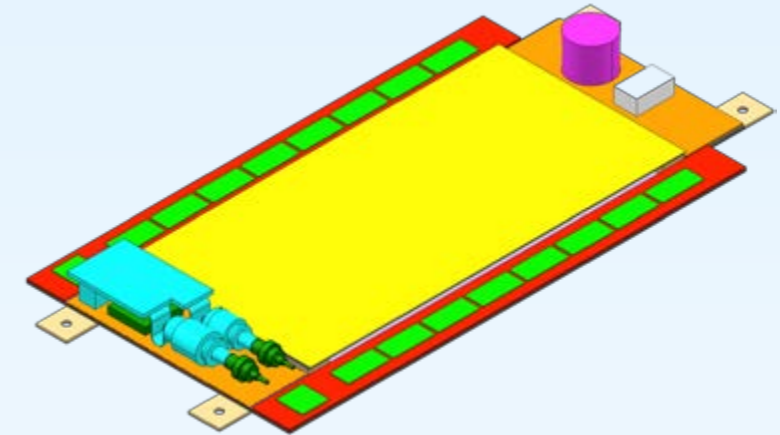
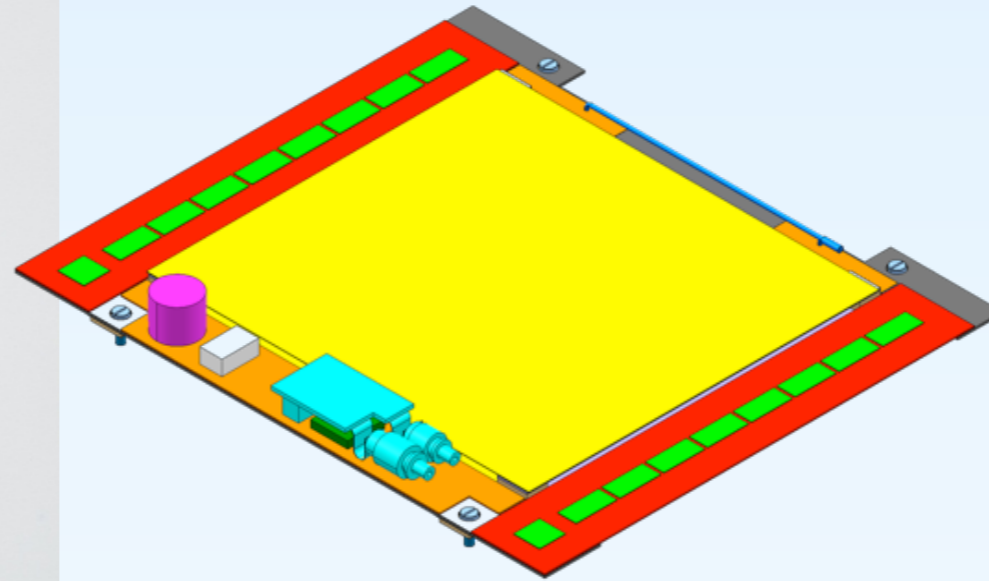
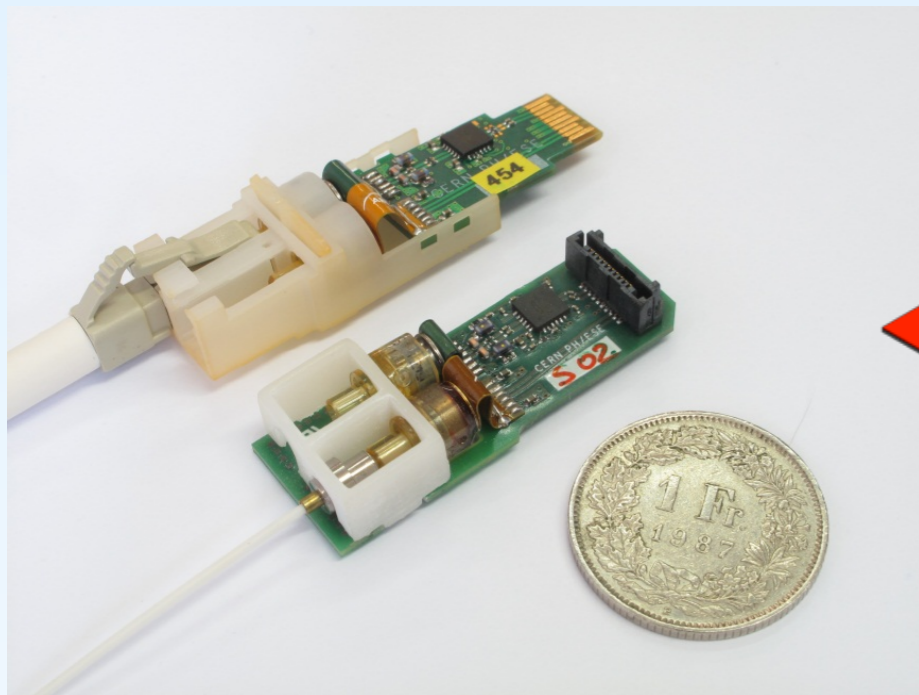
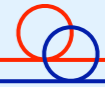
- 1 mA leakage current adds 1.7 dB sensitivity penalty
- Not clear that removal of DC-current is possible beyond this?

Power Dissipation

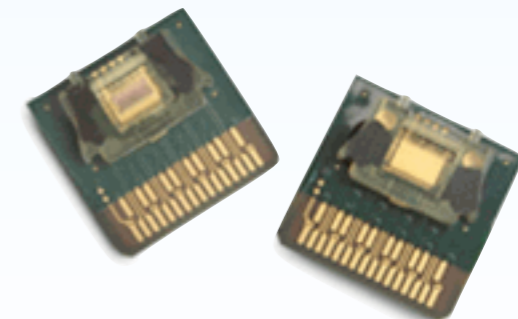


- Current Versatile Link modules (5 Gb/s)
 - Tx draws approx. 100 mA from 2.5 V
 - Rx draws approx. 50 mA from 2.5 V*Call it 400 mW per TRx*
- Prospect of reducing this by factor of 2 seems do-able
 - Need to work much harder on ASIC and finding a lower-power component to find further factors of reduction
 - To be checked with further iterations of laser driver ASICs

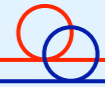
Size



- Could perhaps fit components packaged in industry std. size packages for Tracker 2S (and PS) modules
- Further size reduction requires custom packaging effort
 - To be pursued within VL+ follow-up project
- Only cost-effective with volume



Discussion



- Are there new technologies out there that promise to be significantly more rad hard, smaller and lower power?
- Do we have to push the opto-electronics out of the innermost regions?
- Other mitigation strategies?